| Electronic Patent | Application F | ee Transm | ittal | | |
|---|--|-----------|--------|-------------------------|--|
| Application Number: | 10571142 | | | | |
| Filing Date: | 22-Nov-2006 | | | | |
| Title of Invention: | Semiconductor substrate cutting method | | | | |
| First Named Inventor/Applicant Name: | Kenshi Fukumitsu | | | | |
| Filer: | Joseph John Buczynski/Towanna Bolling | | | | |
| Attorney Docket Number: | 46884-5461 (222847) | | | | |
| Filed as Large Entity | | | | | |
| U.S. National Stage under 35 USC 371 Filing | Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total ii USD(\$) | |
| Basic Filing: | ' | | | | |
| Pages: | | | | | |
| Claims: | | | | | |
| Miscellaneous-Filing: | | | | | |
| Petition: | | | | | |
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| Patent-Appeals-and-Interference: | | | | | |
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| Patent-Appeals-and-Interference: Post-Allowance-and-Post-Issuance: Extension-of-Time: | | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|----------------|-------------------|----------|--------|-------------------------|
| Miscellaneous: | | | | |
| | Total in USD (\$) | | | 1110 |